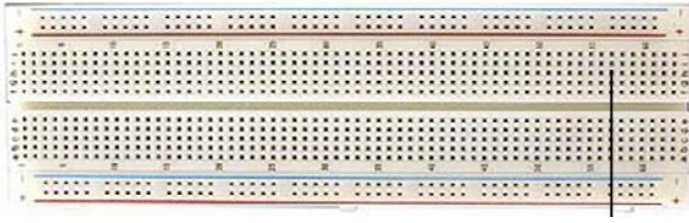
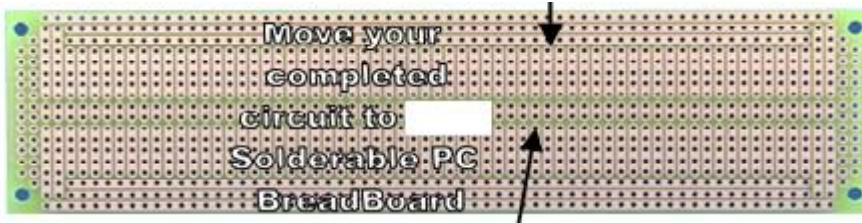


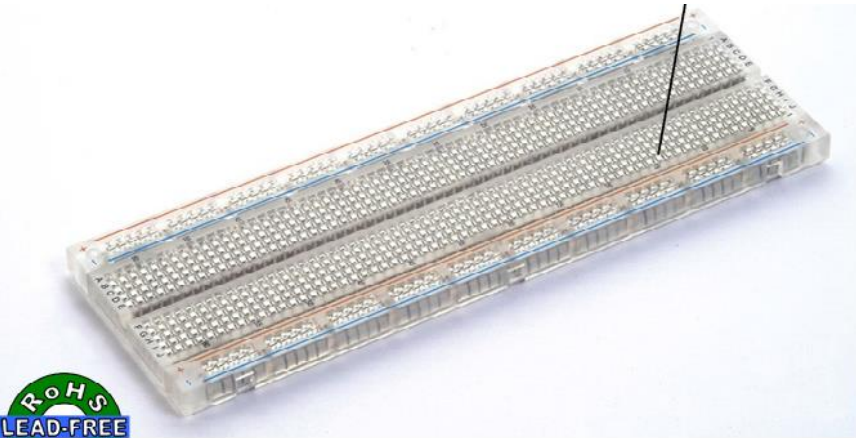
830 tie point solderless "plug-in" breadboards provide a quick way to build and test circuits for experimentation or when learning electronics.



830 tie-point plug -in Solderless Breadboard, ABS plastic with color legend 1 IC/Circuit Area, 630 tie-points , 2 Distribution strips, 200 tie points, Size: 6.5 x 2.2 x 0.3 in (165.1mm x 54.6mm x 8.5mm)



Transparent 830 tie point plug in Solderless Breadboard Transparent ABS Plastic with color legend
1 IC/Circuit Area, 630 tie points
2 Distribution strips, 200 tie points
Size: 6.5 x 2.2 x 0.3 in (165.1mm x 54.6mm x 8.5mm)



Solderless BreadBoard Specifications

Body Material: White ABS Plastic with Black Printed Legend
Body Material: White ABS Plastic with Color Printed Legend
Body Material: Transparent ABS Plastic with Color Printed Legend

Hole Pitch/Style: 0.1" (2.54 mm), Square Wire Holes

ABS Heat Distortion Temperature: 84° C. (183° F.)

Spring Clip Contact: Phosphor Bronze with Plated Nickel Finish
Contact Life: 50,000 insertions
Rating: 36 Volts, 2 Amps

Insertion Wire Size: 21 to 26 AWG
0.016 to 0.028 inches diameter (0.4 to 0.7mm diameter)

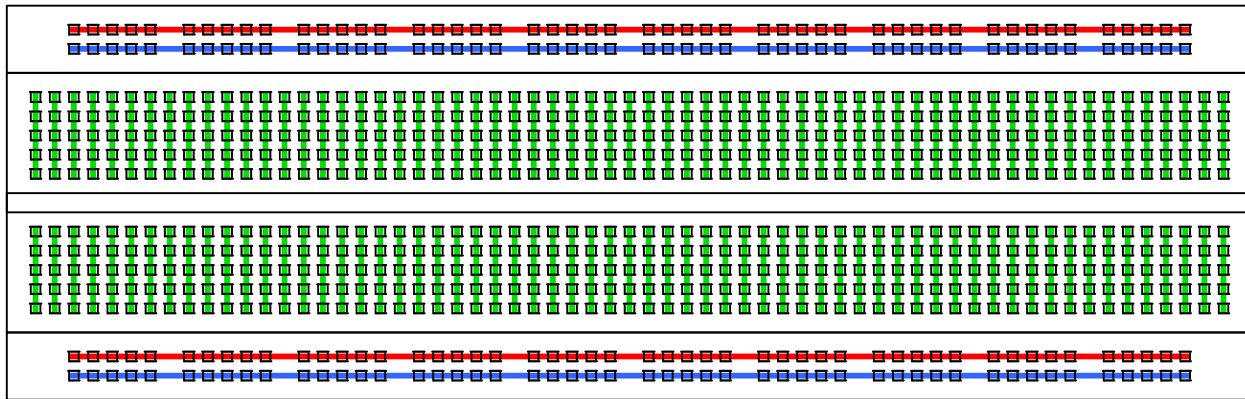
Backing: Peelable adhesive tape for attaching to a surface.
Metal back plate provided with 830 tie point breadboards.

Metal Back Plate Thickness: 0.031 inches (0.8mm)

Lead-Free and *RoHS Compliant*.



Internal Connections



The breadboards have 63 vertical columns on top and 63 columns below. Each column has 5 connected holes each (the green lines). This is the circuit area. There are also 4 “rails” (or distribution strips) for power and ground running horizontally (the red and blue lines).

A distribution strip can be used to carry a signal if it is not needed for power or ground.

Solderless BreadBoard FAQ

Q: What circuit frequencies can I use with a plug-in solderless breadboard?

A: Due to large stray capacitance (from 2-25pF per contact point), the inductance of connections, and a relatively high and not very reproducible contact resistance, solderless breadboards are limited to operate at relatively low frequencies, usually less than 10 MHz, depending on the nature of the circuit. The relatively high contact resistance can also be a problem for some DC and very low frequency circuits.

Source <http://en.wikipedia.org/wiki/Breadboard>

Higher frequency operation may be possible in some cases, depending upon the circuit requirements.

Note: Solderable PC BreadBoards, such as, will provide lower stray capacitance and lower connection resistance which may allow higher frequency operation for some circuits.

For circuits sensitive to small changes in values, component adjustments may be needed when the circuit is moved from a plug-in breadboard to a Solderable PC BreadBoard, due to these small differences.

Q: Can I plug DIL or SIL connector headers into the breadboard?

A: Yes. The square pin of a standard 0.1" spacing header is typically 0.025 inches wide. This is within the 0.016 to 0.028 inch wire insertion size range recommended for the breadboard.

Solderless BreadBoard NSFAQ

Q: Who invented the solderless breadboard?

A: US Patent #203938 was awarded to Ronald J. Portugal of EI Instruments Inc. in 1971.

Q: Why is phosphorus added to the bronze used in the contacts?

A: Phosphor bronze is an alloy of copper with 3.5 to 10% of tin and a significant phosphorus content of up to 1%. The phosphorus is added as deoxidizing agent during melting.

These alloys are notable for their toughness, strength, low coefficient of friction, and fine grain. The phosphorus also improves the fluidity of the molten metal and thereby improves the castability, and improves mechanical properties by cleaning up the grain boundaries.

Source http://en.wikipedia.org/wiki/Phosphor_bronze

Introducing Solderable PC BreadBoards

A **solderable PC breadboard** is a prototyping printed circuit board (PCB) with a connection pattern the same as a **solderless breadboard** (plug-in breadboard).

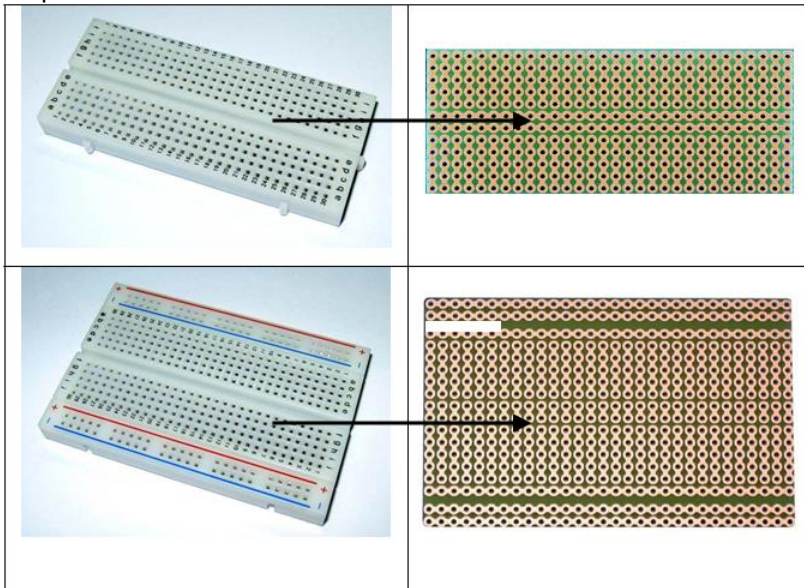
Many electronics hobbyists are familiar with using breadboards to build and test circuits. Breadboards allow circuits to be quickly built and modified as needed, and they are reusable. However, breadboard circuits aren't very rugged. Movement or vibration can easily cause wires and parts to fall out.

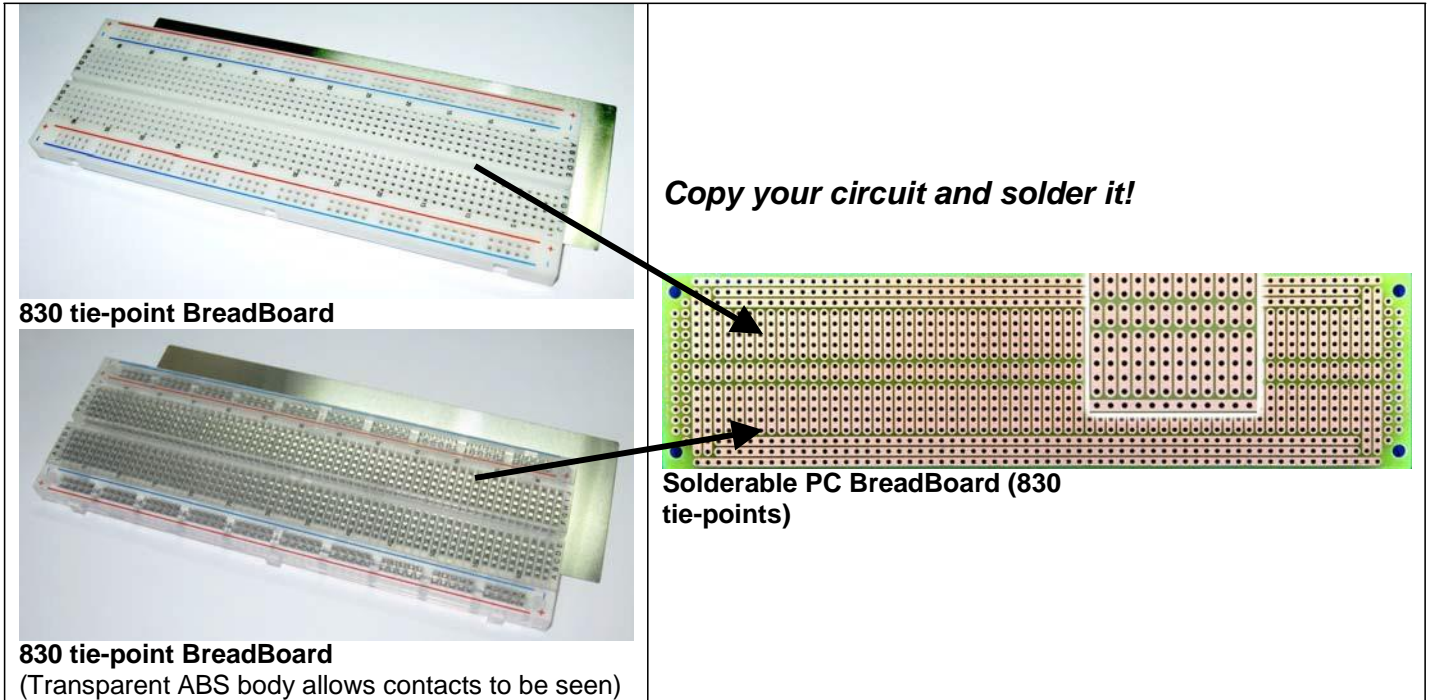
Once a circuit is working, a more rugged, permanent circuit is often needed. Soldering the parts on a PCB protoboard makes the connections durable. Since PC breadboards have the same patterns as breadboards, it is easy to construct a soldered permanent circuit based on a plug-in breadboard prototype.

PC breadboards come in various sizes to match the different solderless breadboards available. The most common sizes are the 300, 400, and 830 tie-point breadboards.

Solderable PC BreadBoards

provides solderless breadboards and solderable breadboards in the most popular sizes.





1 Copying a Circuit

It is better to “copy” a circuit than to “move it” when going from solderless breadboard to a solderable PC breadboard. Purchase 2 sets of components, if that isn’t too expensive. Use the second set of components to build an identical circuit on the PC breadboard, referring to the circuit on the plug-in breadboard.

Copying a circuit is easier than moving it part by part because one can refer to the still working prototype. Copying the circuit in this manner allows you to compare the soldered board to the working original in case there are problems and it doesn’t work immediately. The two circuits can also then be tested and measured to ensure they are working identically.

2 Bonus Pads

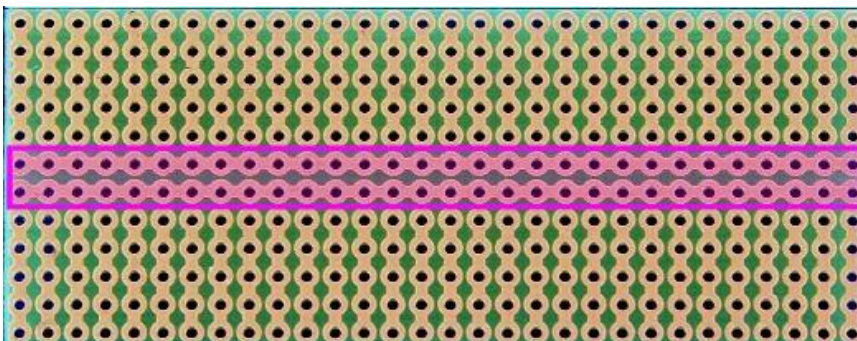
A solderless breadboard has areas where there are no connection points, for example, down the centreline (under the plugged in ICs) and between the circuit area and the power strips.

Solderable PC BreadBoards often have extra pads in these otherwise unusable spaces called **Bonus Pads**.

If a PC board is being used for general-purpose use, these bonus pads can be used for mounting extra components, and they can make some parts easier to fit.

If a PC board is being used to transfer a circuit from a solderless breadboard, these extra pads may be ignored.

2.1 Bonus Pads



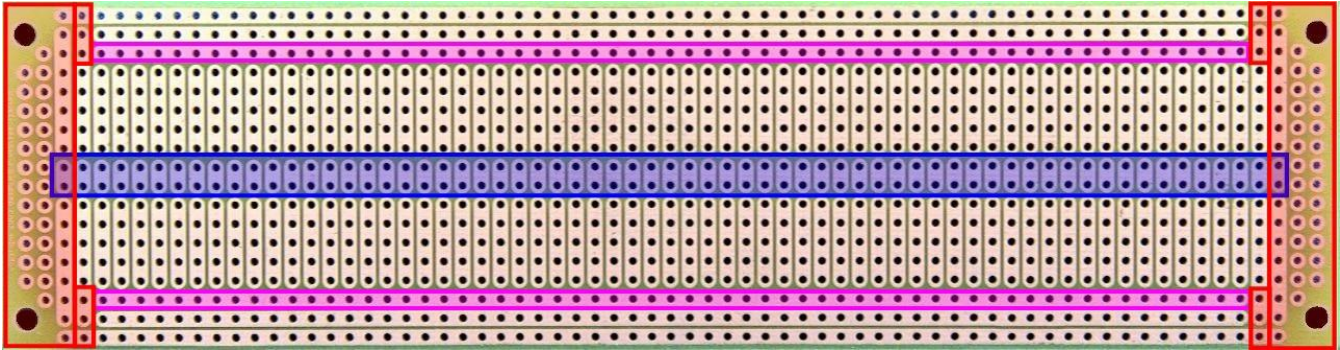
Vertical circuit connections are in the same pattern as those on a solderless breadboard.

The bonus pads are the two distribution strips running the length of the board as bonus pads (the pink tracks in the photo). They can be used to carry power or signals.

The bonus pads include the 2-hole pairs running along the centerline (the pads shown in blue). These pads allow a dual in-line (DIL) header to be installed if required for off-board signals. The board has two extra distribution strips (shown in pink). They are located with spacing 0.1" from the circuit area to allow parts with that spacing to bridge the gap.

The outer two distribution strips are located 0.25" away from the circuit area. The distribution strip holes line up with the column in the circuit area. This makes the board easier to use as a general-purpose proto-board..

2.2 Bonus Pads

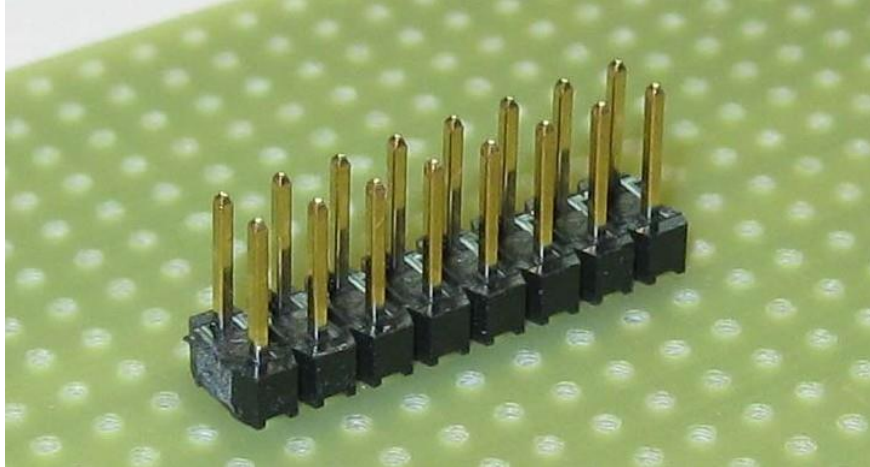


The bonus pads include the 2-hole pairs running along the centerline (the pads shown in blue above). These pads allow a dual in-line (DIL) header to be installed if required for off-board signals.

The board is 0.6 inches wider than a breadboard. Two extra columns, 4 mounting holes, and some round pads are provided in the extra area (shown in red above).

It has two extra distribution strips (shown in pink above). They are located with spacing 0.1" from the circuit area to allow parts with that spacing to bridge the gap. Note that the outer two distribution strips are located on 0.1" centers from the circuit area, which is helpful for general-purpose use. The distribution strips on the solderless breadboard are positioned an additional 0.05 inch further outwards.

Distribution strips have extra holes not found on the breadboard. The solderless breadboard strips have groups of 5 holes and then a space with no hole. The BR1 strips have a hole every 0.1". The distribution strip holes line up with the columns in the circuit area on breadboards.



DIL (Dual In-Line) Header Installed On A Solderable PC Board

With the centerline bonus pads, it is possible to use a DIL header without cutting tracks.

3 Distribution Strip Spacing Differences

The distribution strip spacing on some solderable PC breadboards is slightly different than the solderless plug-in breadboards. This has been done to keep the holes on 0.1" spacing centers to make them more useful as general-purpose prototyping boards.

As mentioned in the Bonus Pads section, the strips are located the same distance from the centerline, but they are offset to line up with the circuit area columns.

The BR1 distribution strips are moved inwards slightly by 0.050" so that all of the holes on the board are on 0.1" centers.

4 Off-board Connections

Here are some suggestions for connecting power and other off-board signal connections to a solderable PC breadboard:

1. Use stranded 22 AWG wire for wire connections running off-board to other boards or devices. Solid 22 AWG wire will crack and break after being flexed many times. Stranded wire can be flexed more times.
2. Use a strain relief to keep the wire from flexing at the point where it is soldered. Solder will wick up stranded wire when it is soldered, and make it stiff and susceptible to cracking. Using a strain relief causes the wire to flex away from the solder joint, where it is more flexible.
3. Use headers or other connectors with removable plugs for off-board connections. This allows more rugged cables to be used, and worn out cables can be replaced.

